

# MM5130

## DC to 26 GHz High Power RF Switch



## Product Overview

### Description

The MM5130 device is a high-power SP4T micro-mechanical switch offered by Menlo Micro. Menlo Micro has developed a new Ideal Switch® fabrication process and applied it to DC and wideband RF/microwave switch applications. This innovative technology enables highly reliable switches capable of 25 W power handling. The MM5130 provides ultra-low insertion loss and superior linearity as an SP4T from DC to 18 GHz, and greater than 3 billion switching cycles.

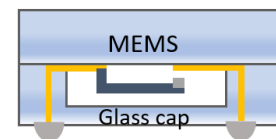
The MM5130 can also be configured in Super-Port mode that extends the frequency operation to 26 GHz. The MM5130 is an ideal solution for replacing large RF electromechanical relays, as well as RF/microwave solid-state switches in applications where linearity and insertion loss are critical parameters. The four switch channels are individually controllable by applying a gate voltage to the corresponding RF GATE pin.

### Features

- DC to 26 GHz Frequency Range
- 25 W (CW), 150 W (Pulsed) Max Power Handling
- Low On-State Insertion Loss: 0.3 dB @ 6.0 GHz
- High Linearity, IIP3 95 dBm Typical
- 25 dB Isolation @ 6.0 GHz / 45 dB Super-Port Mode
- High Reliability > 3.0 x 10<sup>9</sup> Switching Operations
- 2.5 mm x 2.5 mm WLCSP Package

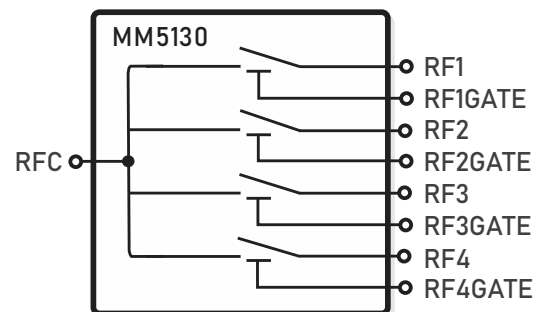
### Markets

- Defense and Aerospace
- Medical Equipment
- Test and Measurement
- Wireless Infrastructure



### Applications

- Switched Filter Banks and Tunable Filters
- High Power RF Front Ends
- Antenna Tuning
- Low-Loss Switch Matrices & EM Relay Replacement



## Electrical Specifications

### Operating Characteristics

#### Absolute Maximum Ratings

Exceeding the maximum ratings as listed in [Table 1](#) below may reduce the reliability of the device or cause permanent damage. Operation of the MM5130 should be restricted to the limits indicated in the recommended operating conditions listed in [Table 2](#).

#### Electrostatic Discharge (ESD) Safeguards

The MM5130 is a Class 0 ESD device. When handling the MM5130, observe precautions as with any other ESD sensitive device. Do not exceed the voltage ratings specified in [Table 1](#).

**Table 1. Absolute Maximum Ratings<sup>1</sup>**

Parameter	Minimum	Maximum	Unit
<b>CW Input Power @ 6 GHz</b>		25	W
<b>Peak Input Power @ 6 GHz</b>		150	W
<b>Open State Voltage Rating / Switch RF1-4 to RFC<sup>2</sup></b>	-150	150	V
<b>Open State Voltage RF1-RF4, RFC to GND, GATE pin to GND Potential<sup>2 3</sup></b>	-150	150	V
<b>Closed State Voltage RFGATE Pins to RF1-RF4, RFC, GND<sup>2</sup></b>	-100	100	V
<b>Hot Switching Voltage<sup>4</sup></b>	-0.5	0.5	V
<b>DC Current Rating/Switch</b>		500	mA
<b>Operating Temperature Range</b>	-40	+85	°C
<b>Storage Temperature Range<sup>5</sup></b>	-65	+150	°C
<b>Mechanical Shock<sup>6</sup></b>		500	G
<b>Vibration<sup>7</sup></b>		3.1	Grms

**Notes:**

1. All parameters must be within recommended operating conditions. Maximum DC and RF power can only be applied during the on-state condition (cold-switched condition).
2. This also applies to ESD events. This is a Class 0 device.
3. RF pins must not be allowed to electrically float during switch operation. See section [Floating Node Restrictions](#) for details on avoiding floating nodes.
4. See section [Hot Switch Restrictions](#) for more information.
5. See section [Storage and Shelf](#) Life more information on shelf and floor life.
6. See JESD22-B104 for mechanical shock test methodology at 1.0 ms, half-sine, 5 shocks/axis, 6 axis.
7. See JESD22-B103 for vibration test methodology at 3.1 G and 30min/cycle, 1 cycle/axis, 3 axis.

## DC and AC Electrical Specifications

All specifications valid over full VBB range and full operating temperature range unless otherwise noted.

**Table 2. DC and AC Electrical Specifications**

Parameter	Minimum	Typical	Maximum	Unit
<b>Operating Frequency Range</b>				
Normal SP4T mode	DC		18	GHz
Super-Port Mode	DC		26	GHz
<b>CW Power @ 6 GHz<sup>1</sup></b>			25	W
<b>Peak Power @ 6 GHz<sup>2</sup></b>			150	W
<b>Insertion Loss</b>				
Normal SP4T mode @ 6 GHz		0.4		dB
Super-Port mode @ 6 GHz		0.4		dB
Normal SP4T mode @ 18 GHz		1.3		dB
Super-Port mode @ 18 GHz		0.8		dB
Normal SP4T mode @ 26 GHz		—		dB
Super-Port mode @ 26 GHz <sup>3</sup>		1.0		dB
<b>Input/Output Return Loss</b>				
Normal SP4T mode @ 6 GHz		15		dB
Super-Port mode @ 6 GHz		15		dB
Normal SP4T mode @ 18 GHz		10		dB
Super-Port mode @ 18 GHz		18		dB
Normal SP4T mode @ 26 GHz		—		dB
Super-Port mode @ 26 GHz <sup>3</sup>		20		dB
<b>Isolation</b>				
Normal SP4T mode @ 6 GHz		25		dB
Super-Port mode @ 6 GHz		45		dB
Normal SP4T mode @ 18 GHz		18		dB
Super-Port mode @ 18 GHz		32		dB
Normal SP4T mode @ 26 GHz		—		dB
Super-Port mode @ 26 GHz <sup>3</sup>		22		dB
<b>Channel to Channel Isolation @ 6 GHz</b>			25	dB
<b>Third-Order Intercept Point (IP3)<sup>4</sup></b>			95	dBm
<b>Second Harmonic (H2)<sup>5</sup></b>			-130	dBc

Parameter	Minimum	Typical	Maximum	Unit
<b>Third Harmonic (H3)<sup>6</sup></b>		-130		dBc
<b>On/Off Switching and Settling Time</b>				
Turn on time <sup>7</sup>		8.5	16	μs
Turn off time		2.5	6	μs
<b>Full Cycle Frequency</b>			10	kHz
<b>On/Off Switch Operations<sup>8</sup> (MM5130-03NDB)</b>				
at 25 °C	3x10 <sup>9</sup>	30x10 <sup>9</sup>		Cycles
at 70 °C		1x10 <sup>9</sup>		Cycles
at 85 °C		0.1x10 <sup>9</sup>		Cycles
<b>DC Steady State Carry Current</b>			500	mA
<b>Off-State RFC to RFOUT Leakage Current<sup>9</sup></b>		15	150	nA
<b>On-State Resistance (R<sub>On</sub>)</b>		1.2	3	Ω
<b>Off-State Capacitance (C<sub>Off</sub>)</b>		15		fF
<b>Video Feedthrough<sup>10</sup></b>		16		mV <sub>Peak</sub>
<b>Gate Bias Voltage (V<sub>BB</sub>)</b>	87	89	91	V <sub>DC</sub>
<b>Gate Voltage Slew Rate</b>	20		200	V/μs
<b>Gate Bias Current</b>		2	10	nA

**Notes:**

1. Measured at +85°C.
2. For 10 % Duty Cycle and 100 μs pulse width, measured at +85°C.
3. Measured on non-adjacent paths, see measured data for details.
4. Measured at +25 °C.
5. Measured at 1.0 GHz and 2.0 GHz fundamental frequency and 35 dBm input power.
6. Measured at 1.0 GHz and 2.0 GHz fundamental frequency and 35 dBm input power.
7. Includes any actuator bounce, settling time to within 0.05dB of final value, and measured with 20 V/us slew rate GATE pin voltage.
8. Measured at 5 kHz cycling rate.
9. Measured with 150 V RFx to 0 V RFC.
10. Performed with 1 MΩ termination.

## Hot Switch Restrictions

The MM5130 is not intended for hot switching applications and care should be taken to ensure that switching occurs at less than 0.5 V. These restrictions on hot switching apply to both normal mode (SP4T) and Super-Port modes of operation. If the MM5130 is used in hot switching applications, the number cycling operations of the device will be degraded. See section [Switch Reliability Test Results](#) for more information.

## Floating Node Restrictions

RF pins must not be allowed to electrically float during switch operation and therefore require some form of DC path to ground to prevent charge accumulation. DC paths can be an inductor or high value resistance which serves as a discharge path. Floating node examples are:

- Unconnected RF pins, resistively terminate or tie to ground.
- Series capacitance coupling which floats RF pin, shunt with DC path to ground.
- Series connection of switches together such as in Super-Port mode without DC path to ground, shunt with DC path or sequenced switching.

See Menlo Micro application note ***Avoiding Floating Nodes*** for detailed explanation of the hazard conditions to avoid and recommended solutions.

## Thermal and Power Handling Considerations

Under normal low power operating conditions, the MM5130 case temperature mimics the environment temperature. However, during high power operation, the case will heat up due to power dissipation within the device.

It is important to keep the device case temperature below 170 °C for continued reliable operation. Based on an environmental hot temperature of 85 °C then a 85 °C rise is allowable due to power dissipation.

This results in a power dissipation limit of 1.13 W within the device. The operating power limit at a given frequency can then be calculated based on the device insertion loss.

Considering an insertion loss of -0.14 dB at 3000 MHz:

Power Handling = Max. Power Dissipation/(1-10<sup>^(Insertion Loss/10)</sup>)

$$= 1.13/0.032$$

$$= 35.6 \text{ W}$$

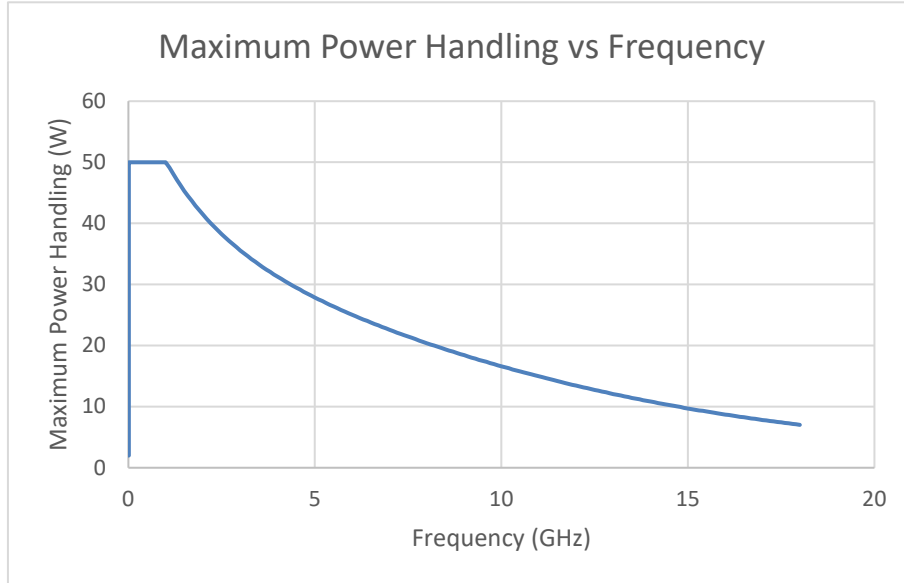
As the MM5130 device insertion loss can also be approximated by a third order polynomial:

$$\text{Insertion Loss (dB)} = -1.1\text{E-}04 * f^3 + 1.2\text{E-}03 * f^2 - 0.024 * f - 0.076$$

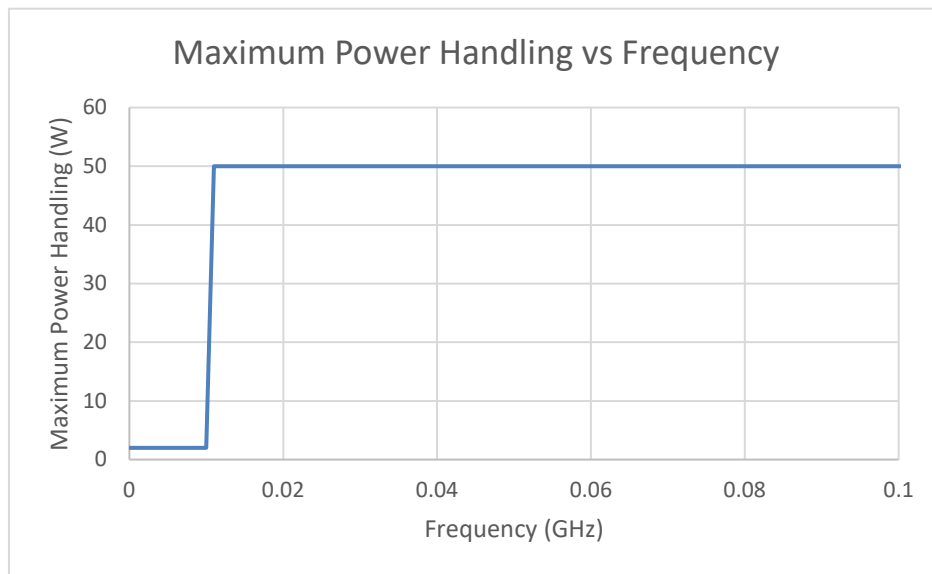
where f is frequency in GHz

This approach does not hold below 10 MHz where the maximum power handling is 2W.

Alternatively, the following chart is provided for the Maximum Power Handling over Frequency

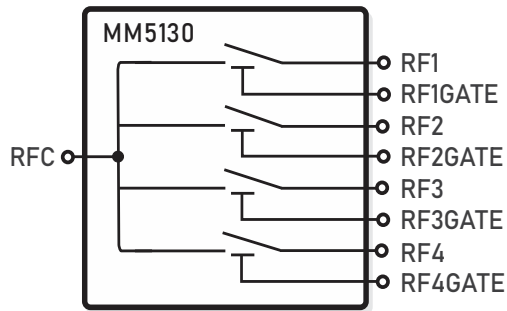


Detail chart from 1kHz to 100 MHz:



## Normal SP4T Mode

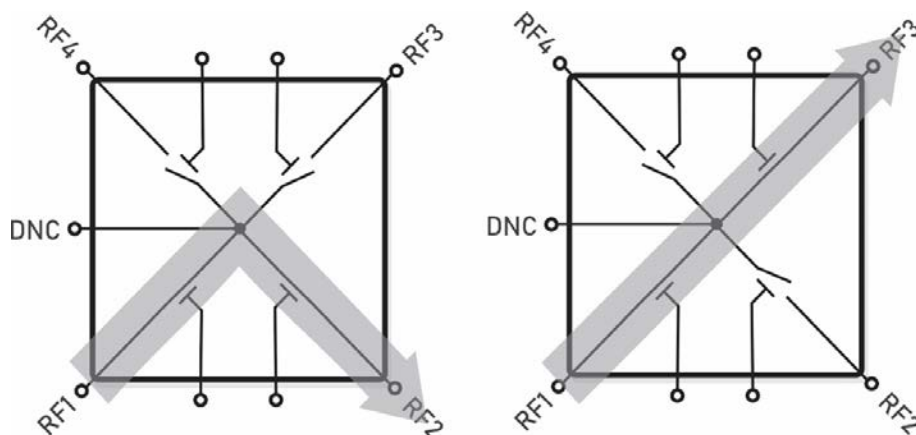
The MM5130 is normally configured as a SP4T, with input on the RFC channel. The RFC is then routed to one of the 4 outputs by biasing the desired RFxGATE pin.



**Figure 1. Normal SP4T Mode Block Diagram**

## Super-Port Mode

The MM5130 provides for an alternate connection method which can provide enhanced performance for certain RF parameters. This configuration is called Super-Port. It consists of bypassing the RFC input port and using the remaining 4 channels as a symmetrically oriented SP3T (or SPST or SPDT if preferred). In this manner, any one of the RF1, RF2, RF3, RF4 channels can be connected to any other channel by biasing both desired channels. When operating in Super-Port mode, slight improvements in RF isolation and return loss can be achieved. Please refer to the [Recommended PCB Layout](#) section with instructions on how to optimize the PCB layout for Super-Port mode.

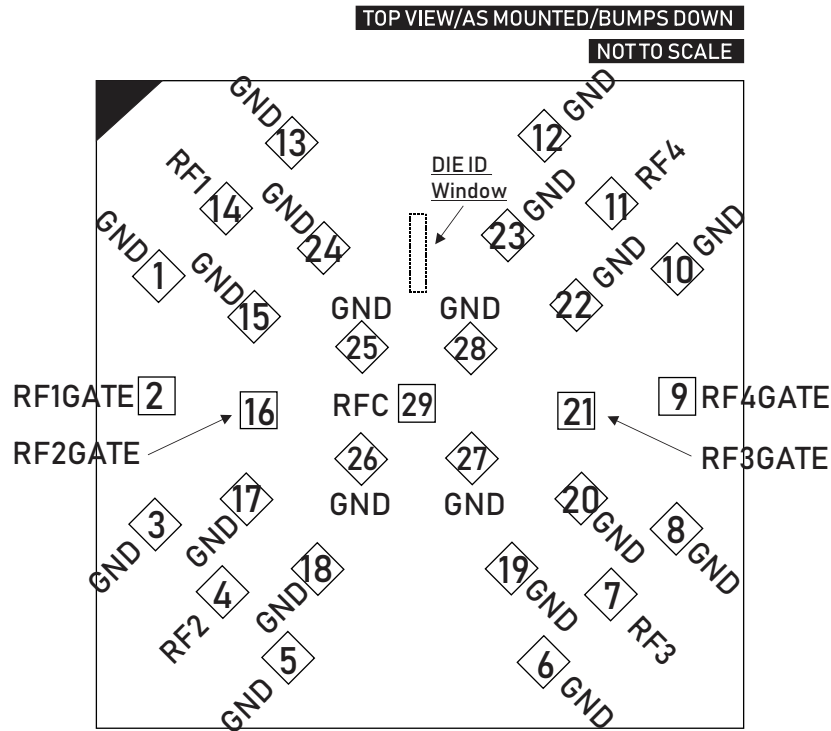


**Figure 2. Super-port Adjacent Path (Left) and Non-adjacent Path (Right)**

RF pins must not be allowed to electrically float during switch operation. See section [Floating Node Restrictions](#) for details of how to avoid floating nodes



## Package/Pinout Information



**Figure 3. MM5130 2.5 mm x 2.5 mm Pinout**

**Table 3. Detailed Pin Description**

Pin Number	Pin Name	Description
1,3,5,6,8,10,12,13,15,17, 18,19,20,22,23,24,25,26,27,28	GND	RF Ground
2	RF1GATE	Control for Switch RF1
16	RF2GATE	Control for Switch RF2
4	RF2	RF Switch 2
7	RF3	RF Switch 3
21	RF3GATE	Control for Switch RF3
9	RF4GATE	Control for Switch RF4
11	RF4	RF Switch 4
14	RF1	RF Switch 1
29	RFC	RF Common

## Applied Gate Voltage vs. RF Switch States

Each switch is individually controllable. Primary usage states are highlighted in bold. Multiple branches may be closed simultaneously, however RF performance is not specified for such states

**Table 4. Applied Gate Voltage vs. RF Switch States (On= Closed, Off = Open)**

RF4GATE (V)	RF3GATE (V)	RF2GATE (V)	RF1GATE (V)	RFC – RF4	RFC – RF3	RFC– RF2	RFC– RF1
<b>Normal SP4T Mode</b>							
<b>0</b>	<b>0</b>	<b>0</b>	<b>VBB</b>	<b>Off</b>	<b>Off</b>	<b>Off</b>	<b>On</b>
<b>0</b>	<b>0</b>	<b>VBB</b>	<b>0</b>	<b>Off</b>	<b>Off</b>	<b>On</b>	<b>Off</b>
<b>0</b>	<b>VBB</b>	<b>0</b>	<b>0</b>	<b>Off</b>	<b>On</b>	<b>Off</b>	<b>Off</b>
<b>VBB</b>	<b>0</b>	<b>0</b>	<b>0</b>	<b>On</b>	<b>Off</b>	<b>Off</b>	<b>Off</b>
0	0	0	0	Off	Off	Off	Off
<b>Other Valid States</b>							
0	0	VBB <sup>1</sup>	VBB <sup>1</sup>	Off	Off	On	On
0	VBB <sup>1</sup>	0	VBB <sup>1</sup>	Off	On	Off	On
0	VBB <sup>1</sup>	VBB <sup>1</sup>	0	Off	On	On	Off
VBB <sup>1</sup>	0	0	VBB <sup>1</sup>	On	Off	Off	On
VBB <sup>1</sup>	0	VBB <sup>1</sup>	0	On	Off	On	Off
VBB <sup>1</sup>	VBB <sup>1</sup>	0	0	On	On	Off	Off
VBB	VBB	0	VBB	On	On	Off	On
VBB	VBB	VBB	0	On	On	On	Off
VBB	VBB	VBB	VBB	On	On	On	On
0	VBB	VBB	VBB	Off	On	On	On
VBB	0	VBB	VBB	On	Off	On	On

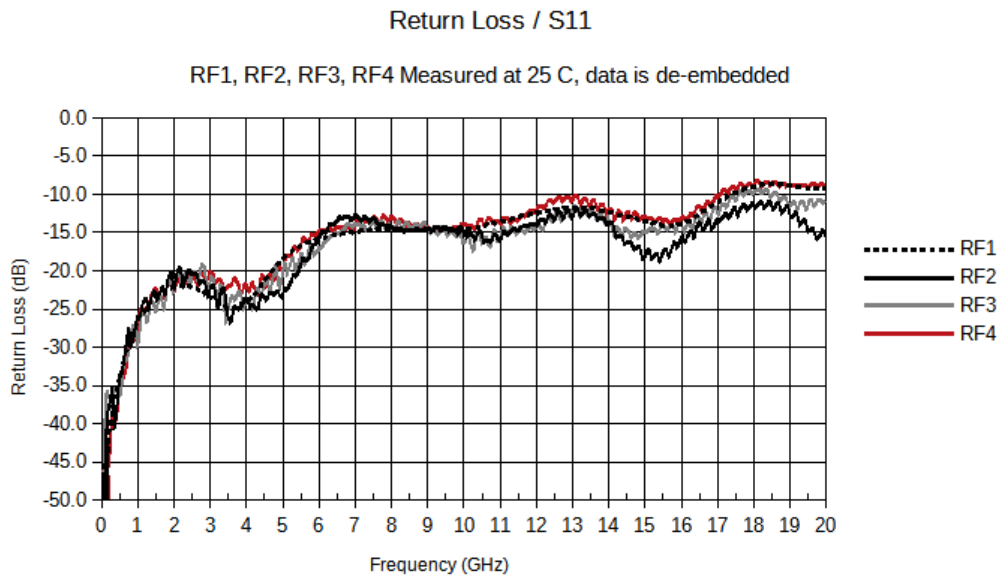
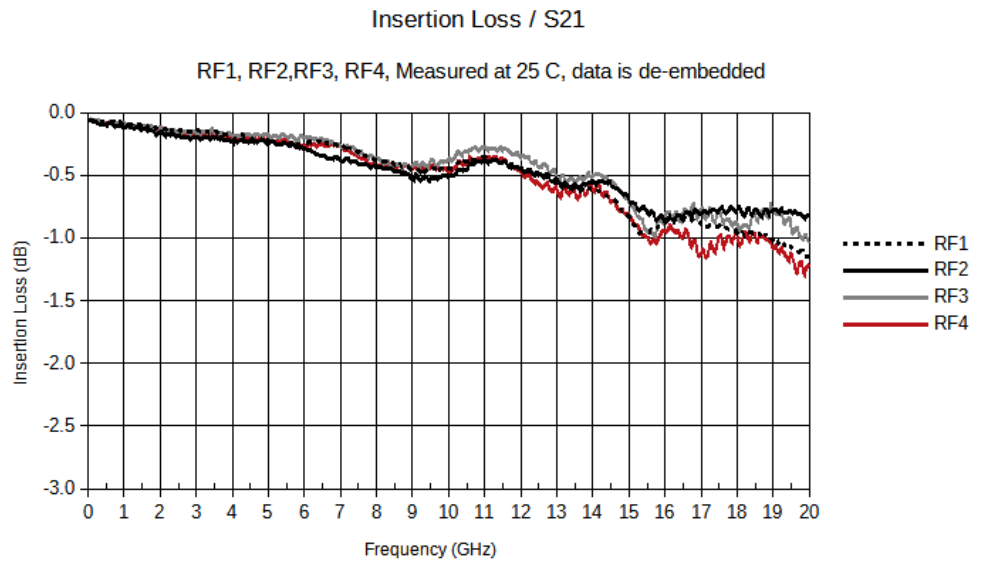
**Notes:**

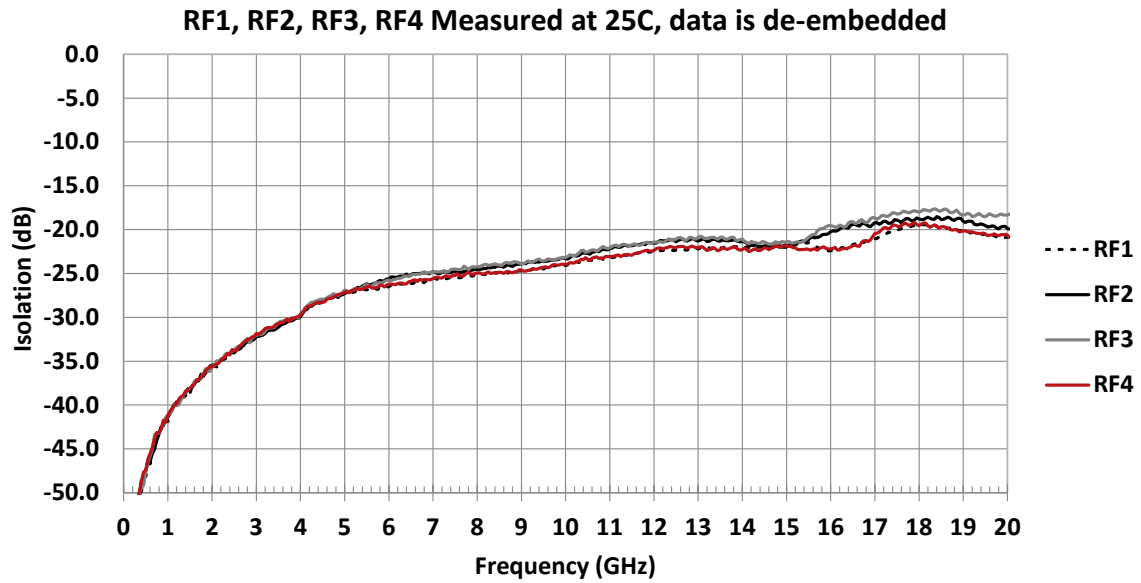
1. Valid states for Super-Port mode.

## RF Performance

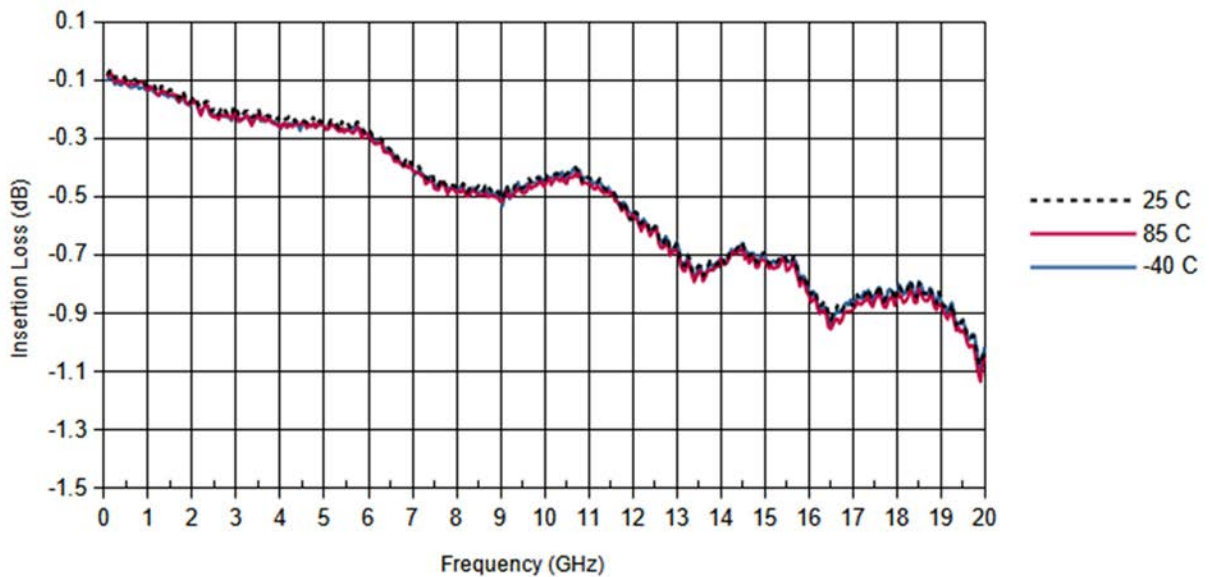
### Normal Mode (SP4T)

Typical device performance measured on evaluation board, de-embedded. For band-limited applications, the performance may be further improved with narrowband matching techniques.



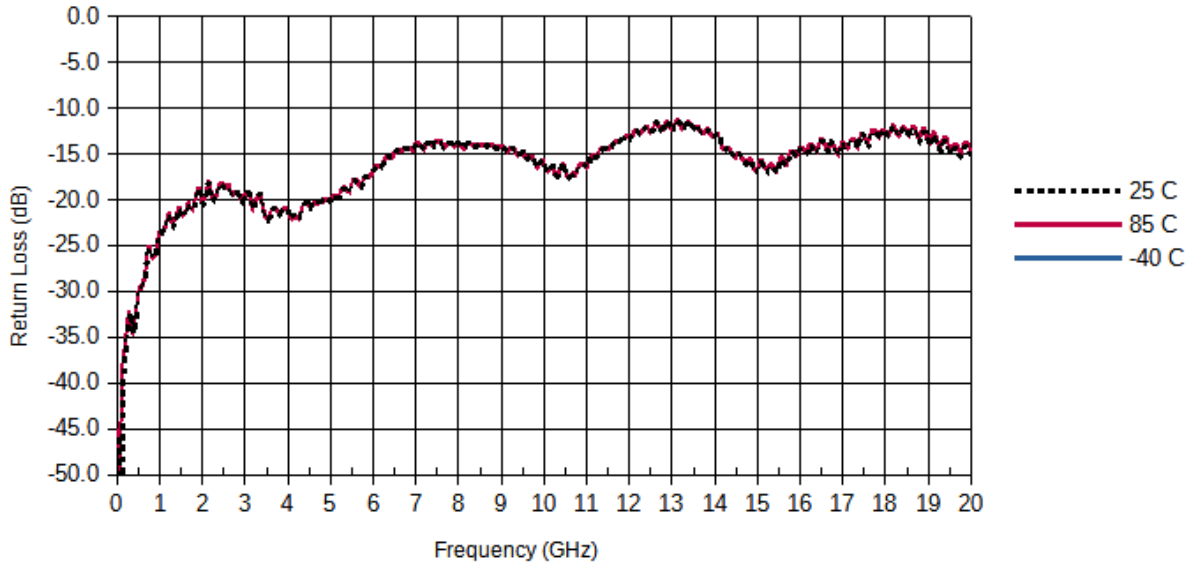
**Off-State Isolation / S21**

**Insertion Loss / S21 for 25 C, 85 C and -40 C**

For channel RF2, data is de-embedded

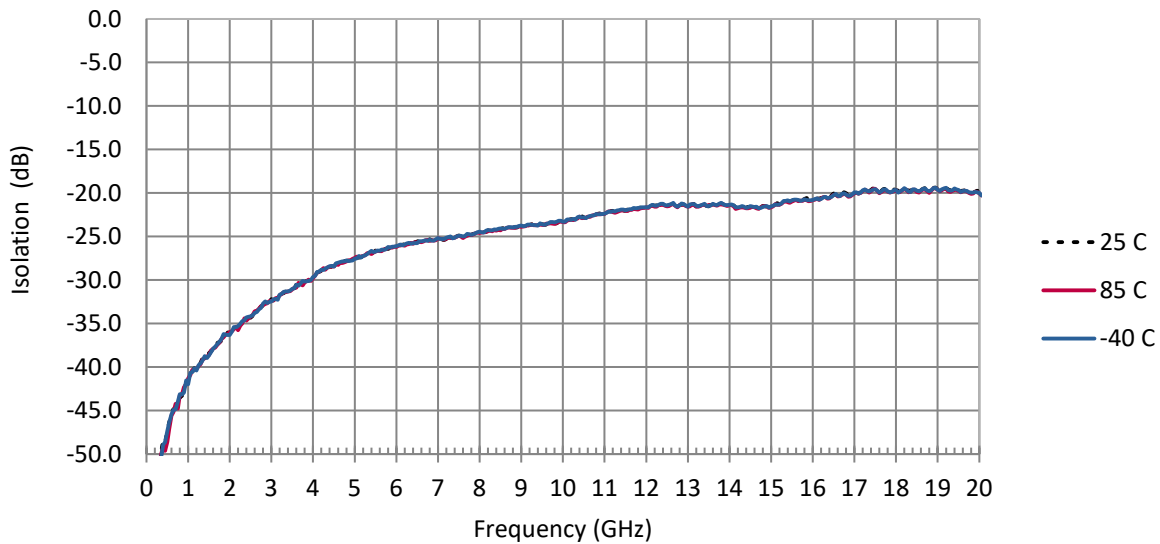


**Return Loss / S11 FOR 25 C, 85 C and -40 C**

For channel RF2, data is de-embedded

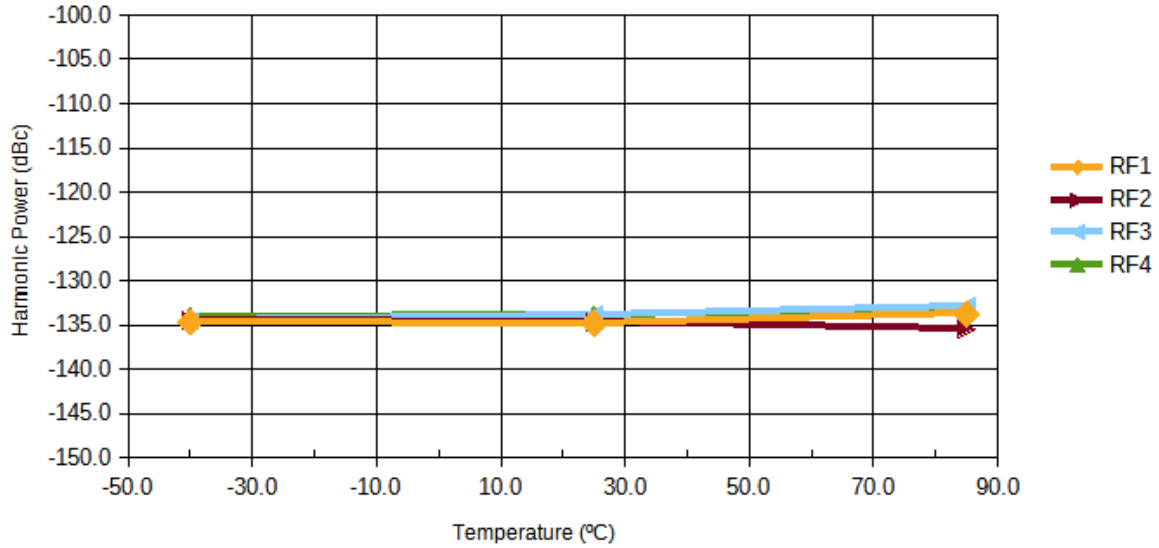

**Off-State Isolation / S21 for 25 C, 85 C and -40 C**

For channel RF2, data is de-embedded



### Second Harmonic Power vs. Temperature

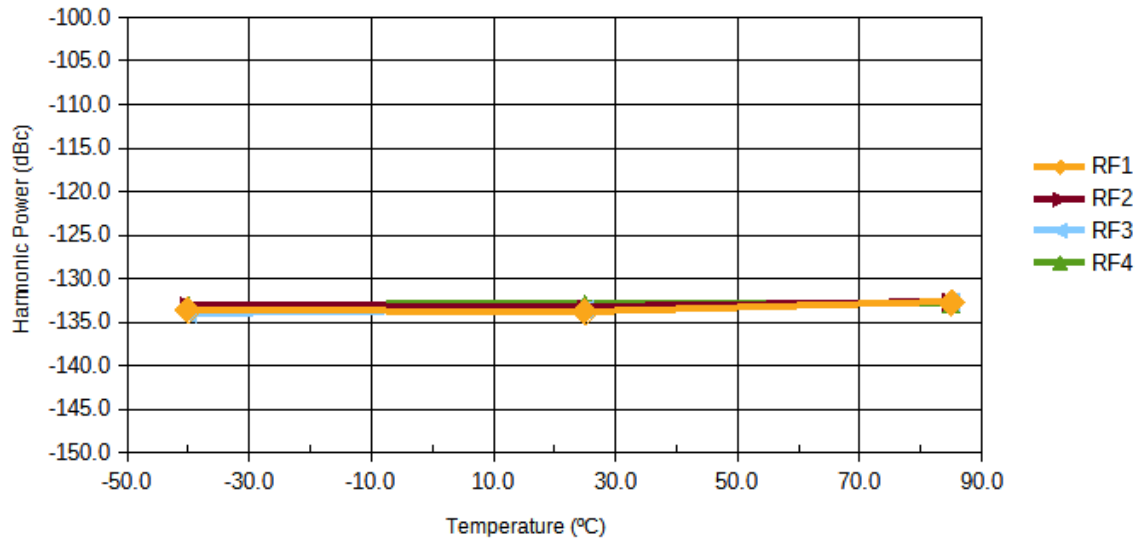
$f_0 = 1.0 \text{ GHz}, 36 \text{ dBm}$



### On / Off Switching Time

#### Third Harmonic Power vs. Temperature

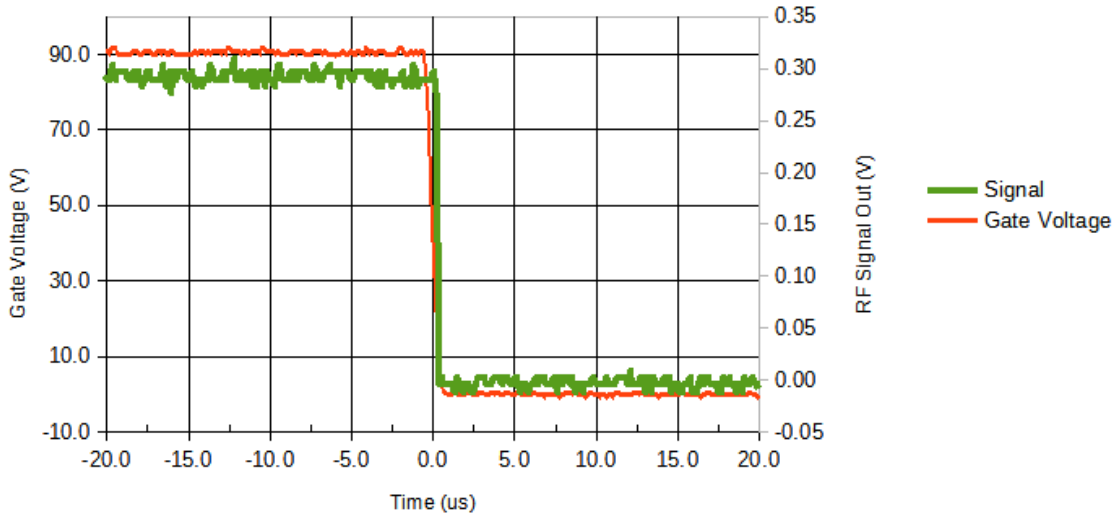
$f = 1.0 \text{ GHz}, 36 \text{ dBm}$



## On / Off Switching Time

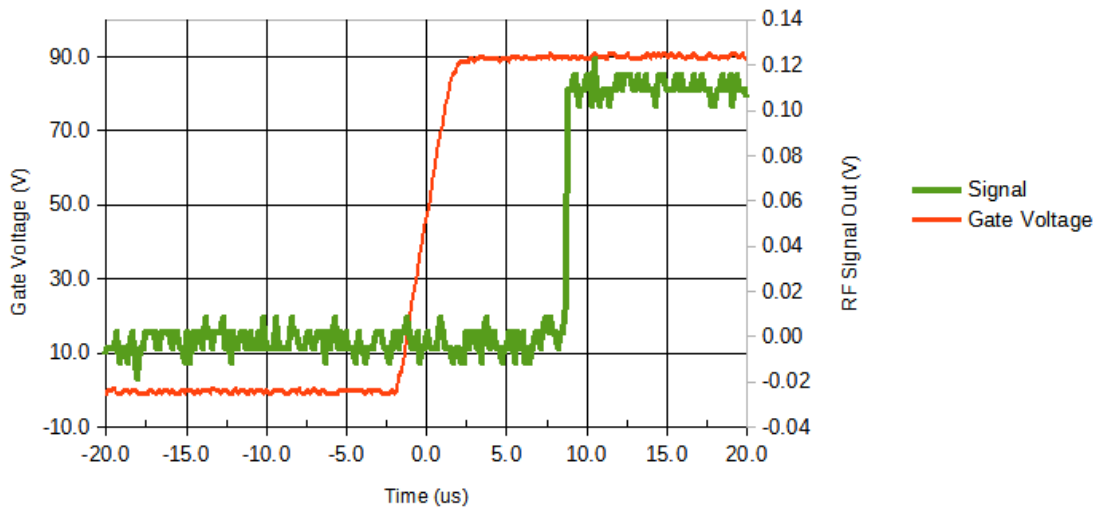
### Switch Off Timing

f = 100 MHz

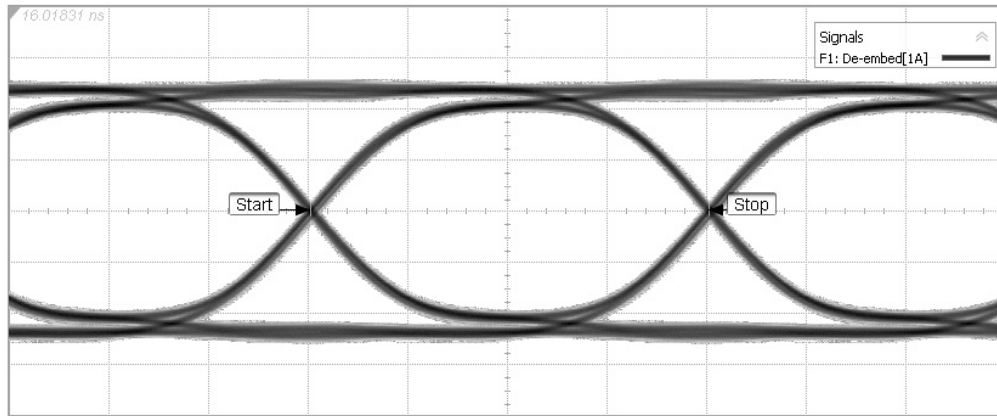


### Switch On Timing

f = 100 MHz



## Single-Ended Eye Diagram Measurement

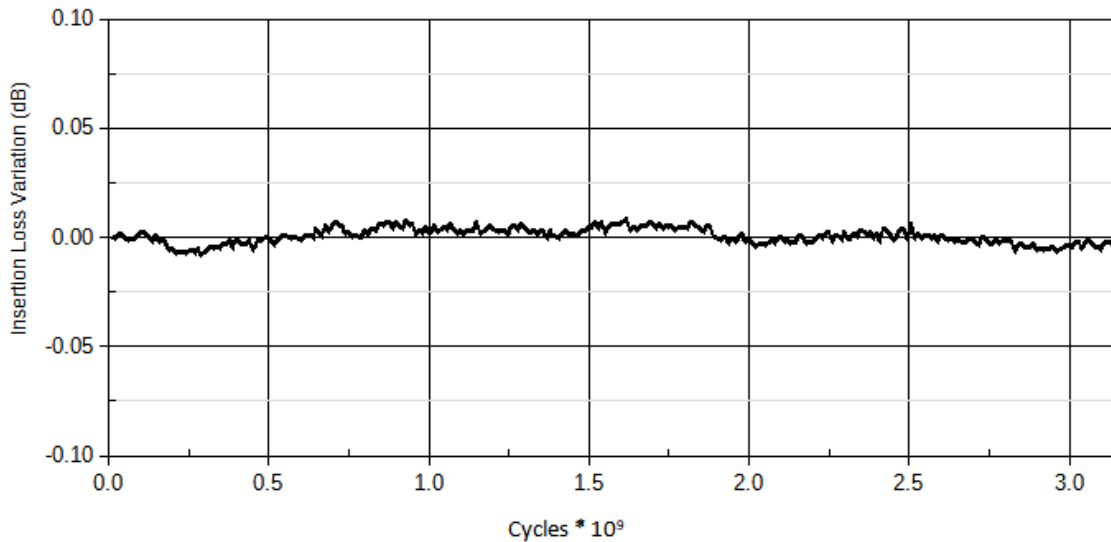


Test Cases	Bit Rate	Eye Height	Eye Width	Jitter (Pk to Pk)	Rise Time	Fall Time
Baseline-Test System	20.000 Gbps	440.00 mV	48.16 ps	1.99 ps	14.99 ps	14.33 ps
MM5130 EVK	20.000 Gbps	339.80 mV	48.20 ps	2.16 ps	24.00 ps	24.34 ps

## Typical Hot-switching Performance

### Insertion Loss Variation over Cycling

Channel RF1 cycled with 10 dBm RF power, measured at 25 C



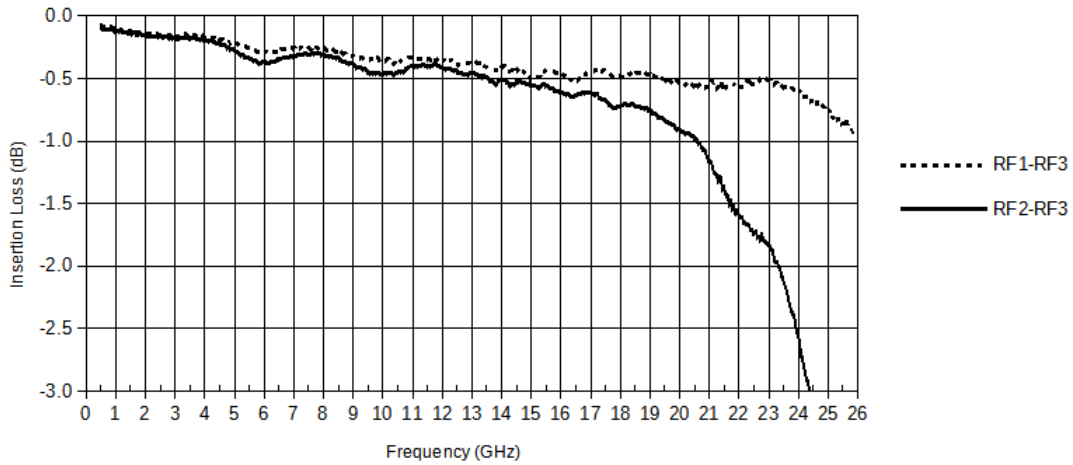


# RF Performance

## Super-Port Mode

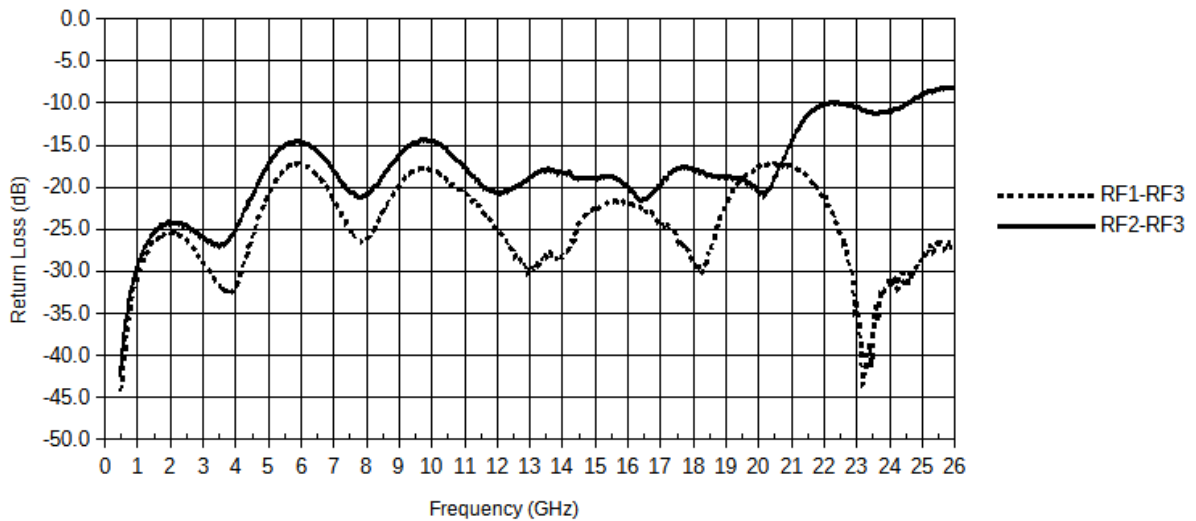
Super-Port Configuration Insertion Loss / S21

RF1-RF3 & RF2-RF3, Measured at 25 C, data is de-embedded



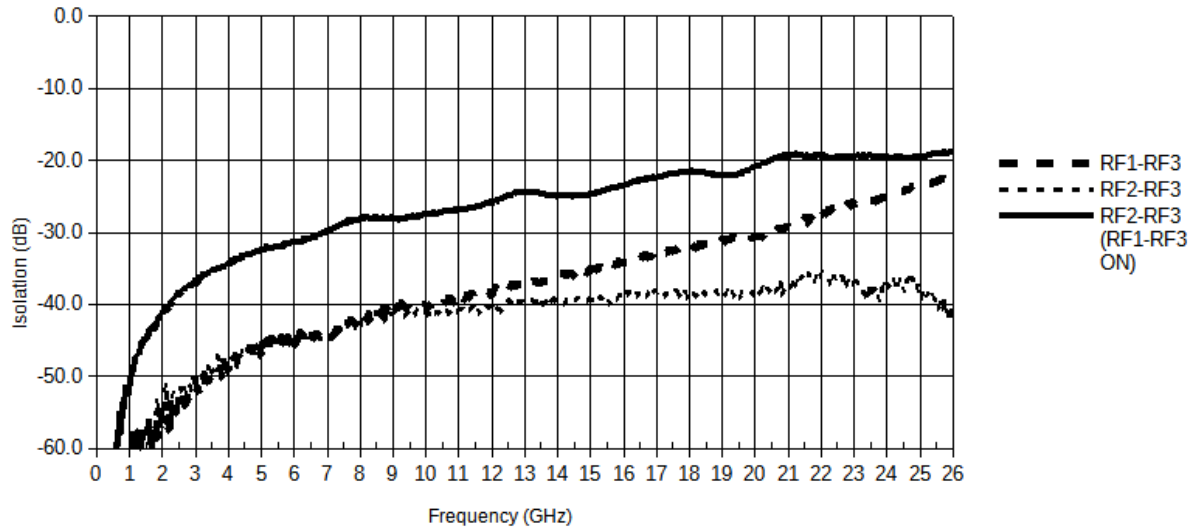
Super-Port Configuration Return Loss / S11

RF1-RF3 & RF2-RF3, Measured at 25 C, data is de-embedded



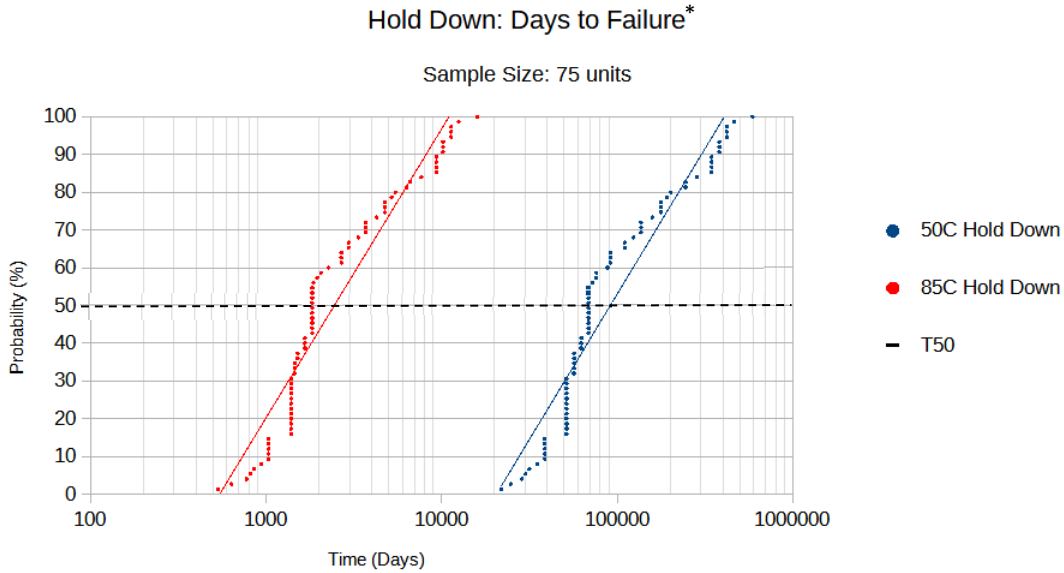
## Super-Port Configuration Isolation / S21

Measured at 25 C, data is de-embedded

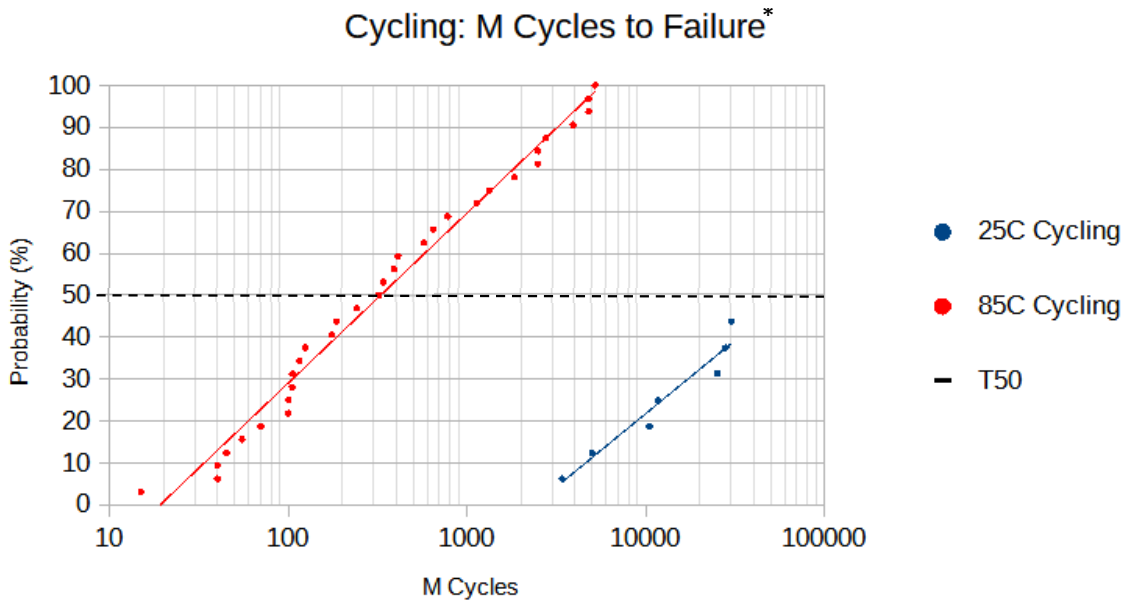


## Switch Reliability Test Results

Switch hold-down duration and actuation cycling reliability test results are plotted below. Hold Down median failure is 68675 days (188 years) @ 50°C and 1836 days (5.0 years) @ 85°C. Cycling median failure is greater than 30 billion cycles @ 25°C and 320 million cycles @ 85°C.



\* Failure is defined as reduced standoff voltage.

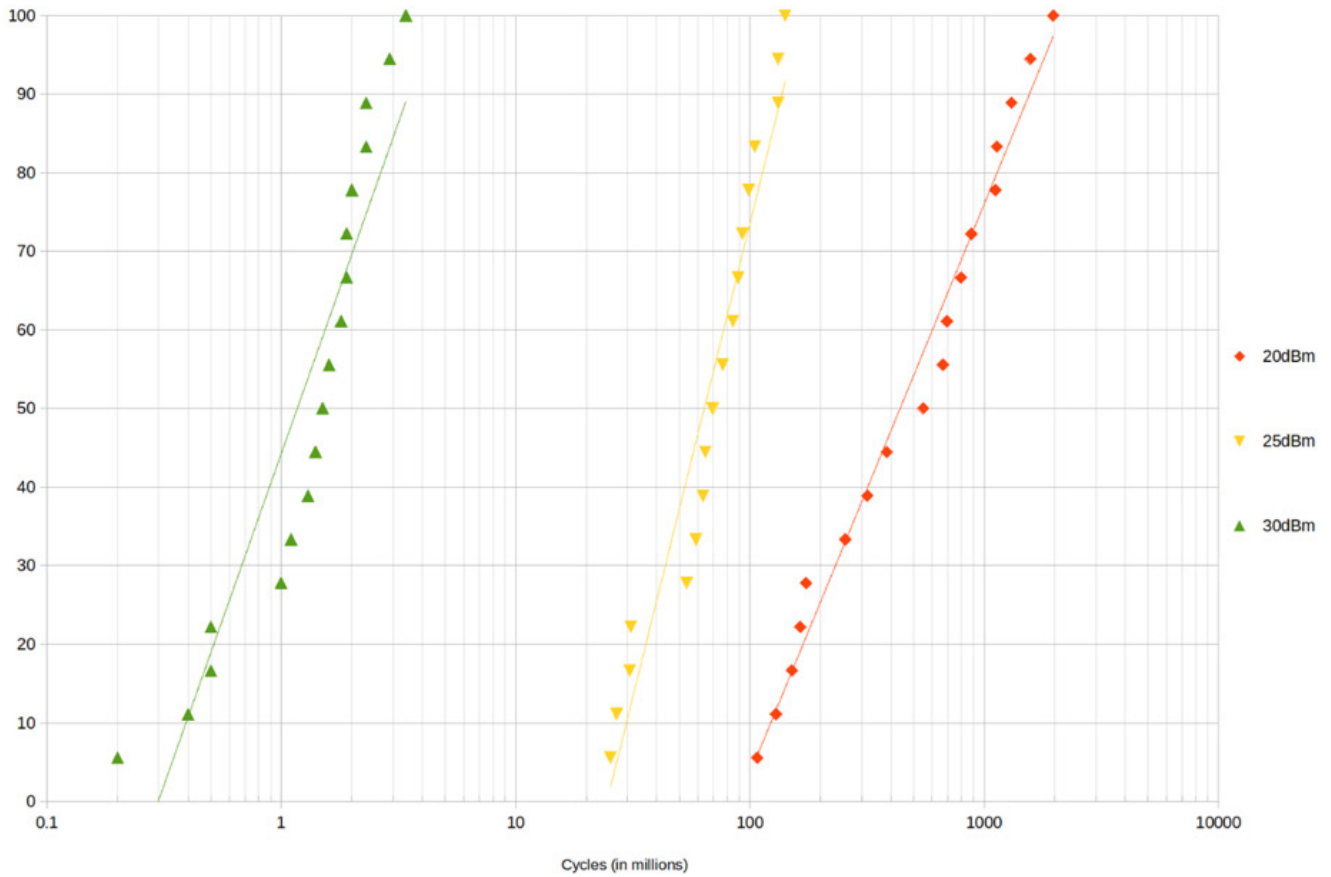


\* Failure definition is stuck closed failure.

Hot switched actuation cycling reliability test results are plotted below from 20 dBm to 30 dBm.

### MM5130 Hot Switch

Measured at Ambient 25C, 500MHz CW RF



## Package Drawing

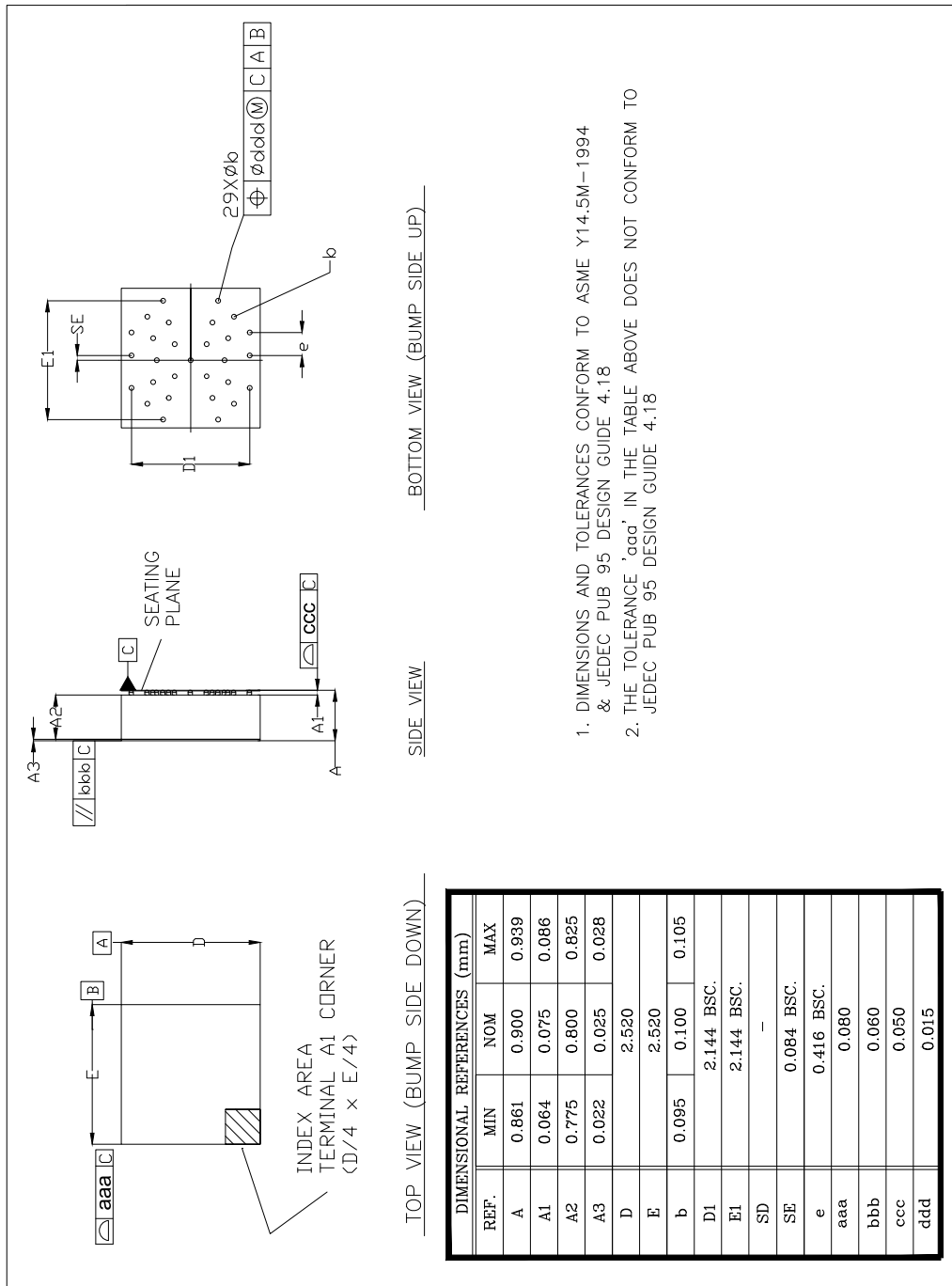
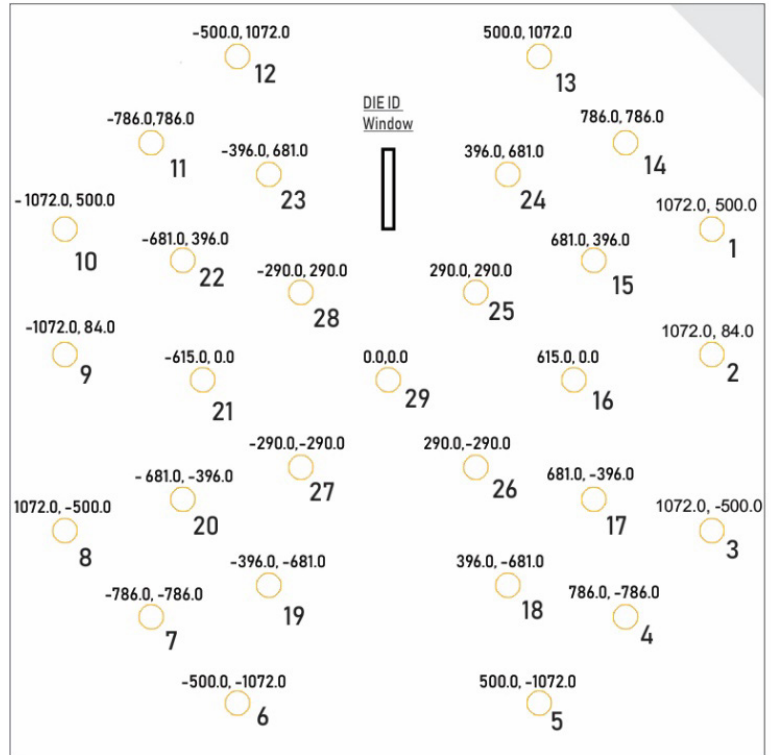


Figure 4. MM5130 Package Drawing

## Bump Coordinates

**BOTTOM VIEW/BUMPS UP (0,0 @ DIE CENTER)**
**μm, TO SCALE**

Pin	X (um)	Y (um)
1	1072	500
2	1072	84
3	1072	-500
4	786	-786
5	500	-1072
6	-500	-1072
7	-786	-786
8	-1072	-500
9	-1072	84
10	-1072	500
11	-786	786
12	-500	1072
13	500	1072
14	786	786
15	681	396
16	615	0
17	681	-396
18	396	-681
19	-396	-681
20	-681	-396
21	-615	0
22	-681	396
23	-396	681
24	396	681
25	290	290
26	290	-290
27	-290	-290
28	-290	290
29	0	0


**Figure 5. Bump Coordinates**

## Recommended PCB Layout

Layout recommendation for connecting the MM5130 with coplanar RF line or grounded coplanar line as used for the MM5130 evaluation board.

For the coplanar RF lines, it is recommended to taper the line to fit the 150  $\mu\text{m}$  recommended landing pad while keeping the spacing to the ground metal constant and identical to the spacing used for the line.

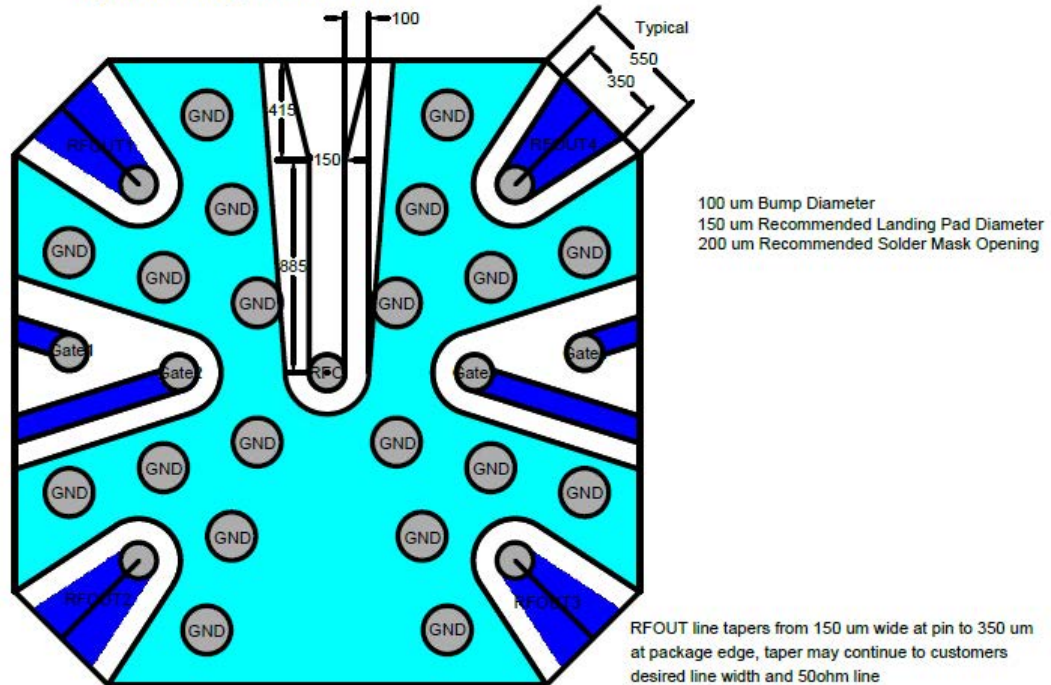
In those two examples (Normal SP4T Mode and Super-Port Mode) a 4.0 mil/0.10 mm spacing is used. Recommended maximum solder resist thickness 20  $\mu\text{m}$ . Routing of the gate control lines is not critical for RF performance.

Ensure the substrate x/y coefficient of thermal expansion (CTE) is 15 ppm/ $^{\circ}\text{C}$  or lower.

### Normal SP4T Mode

Dimensions in  $\mu\text{m}$

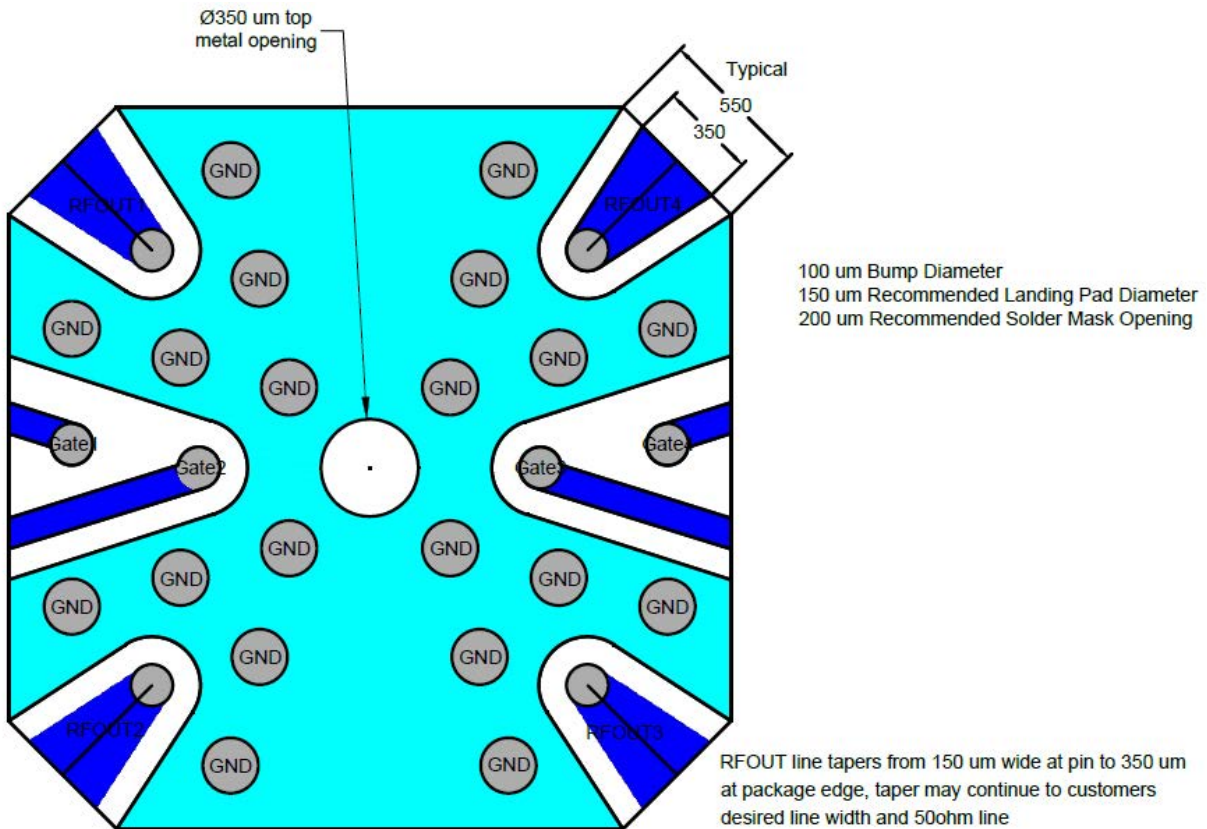
RFC Line tapers from 350  $\mu\text{m}$  at package edge to 150  $\mu\text{m}$  at 415  $\mu\text{m}$  in from edge. Then continues at 150  $\mu\text{m}$  wide until RFC pad. Ground pad tapers from 550  $\mu\text{m}$  at package edge to 350  $\mu\text{m}$  at RFC pad. This is to counter impedance changes due to device ground above the trace.



**Figure 6. Normal SP4T Mode Layout Recommendation**

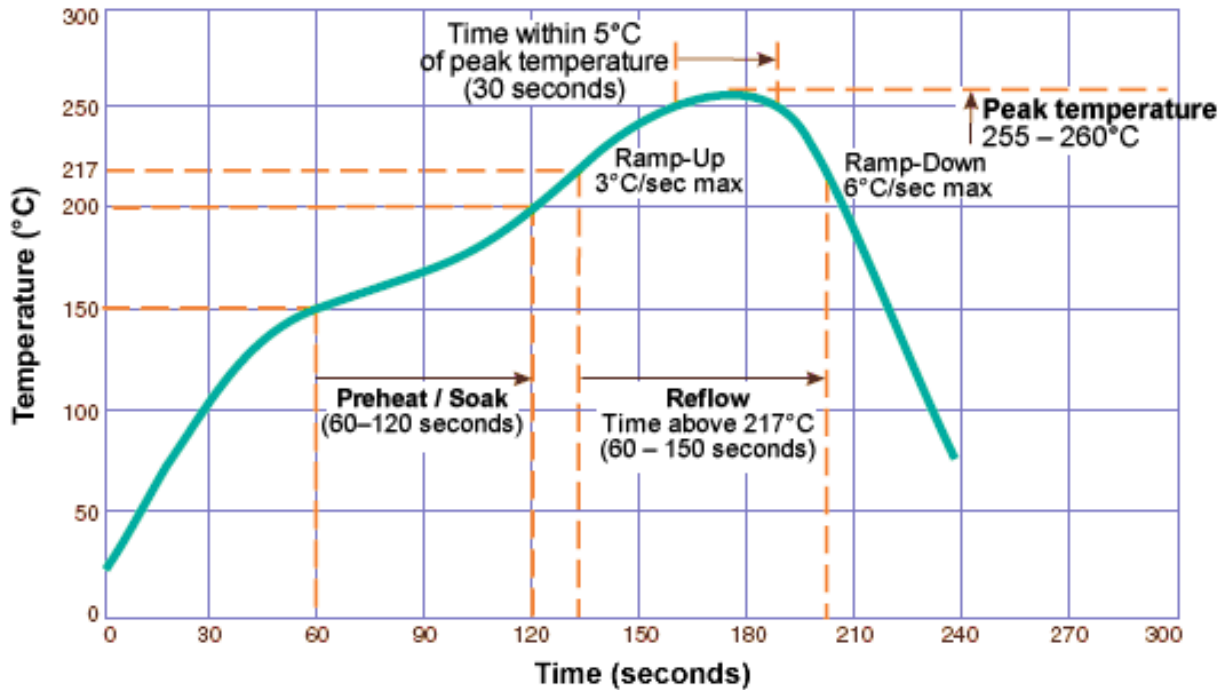
### Super-Port Mode

Dimensions in um





## Recommended Solder Reflow Profile



For detailed information on soldering the MM5130 along with SnPb soldering profile, please refer to the Menlo Micro application note ***WL-FC Assembly Instructions***.

A ROHS-compliant Solder Alloy used is SAC alloy: 96.5% Sn, 3.0%Ag, 0.5%Cu. These are the nominal percentages of the components. This alloy is designed to replace SnPb solders to eliminate Lead (Pb) from the process, requiring a higher reflow temperature. Moisture resistance performance may be impacted if not using the Pb-Free reflow conditions.

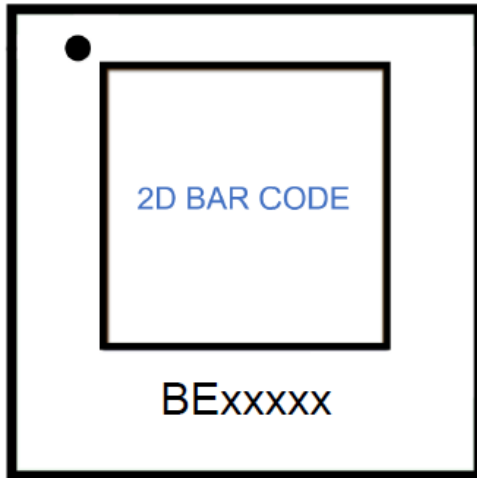
## Storage and Shelf Life

Under typical industry storage conditions (  $\leq 30$  °C/60% RH) in Moisture Barrier Bags:

- Customer Shelf Life: 24 months from customer receipt date
- Extended Shelf Life: 60 months from customer receipt date if re-bagged every 24 months or less.
- Floor life: Moisture Sensitivity Level (MSL) testing is not required for Hermetic package as per JESD47K.
- Do not re-bake

## Package Marking Information

The MM5130 package marking and nomenclature are illustrated in [Figure 7](#).



Dot ● = Pin 1 Indicator  
 Line 1 = 2D Bar Code  
 Line 2 = Human-readable product code

Figure 7. Package Marking Drawing

## Package Materials Information

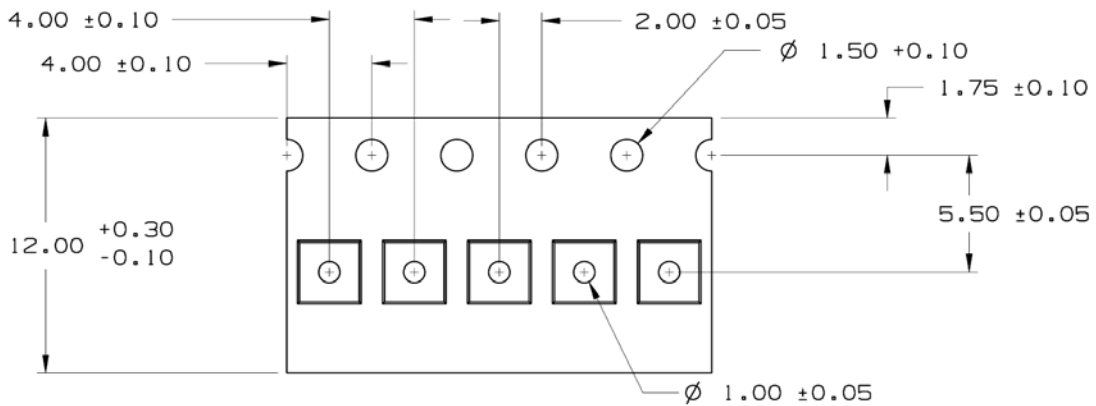


Figure 8. Tape and Reel Drawing

## Package Options and Ordering Information

All Menlo Micro solutions are EAR99 compliant.

Part Number	Package Description	Temp Range	Device Marking <sup>1</sup>
<b>MM5130-03NDB</b>	DC-26GHz - SP4T 2.5 mm x 2.5 mm 29 pin WL-FC Industrial Temp	- 40°C to +85°C	BBxxxxx
<b>MM5130-03NDB-TR</b>	DC-26GHz - SP4T 2.5 mm x 2.5 mm 29 pin WL-FC Industrial Temp Tape and Reel (Qty 250)	- 40°C to +85°C	BBxxxxx
<b>MM5130-03NDC</b>	DC-26GHz - SP4T - (high-temp cycling) 2.5 mm x 2.5 mm 29 pin WL-FC Industrial Temp with Extended Cycling at 85°C	-40°C to +85°C	BBxxxxx
<b>MM5130-03NDC-TR</b>	DC-26GHz - SP4T - (high-temp cycling) 2.5 mm x 2.5 mm 29 pin WL-FC Industrial Temp with Extended Cycling at 85°C Tape and Reel (Qty 250)	-40°C to +85°C	BBxxxxx

**Notes:**

1. Additional markings may be present, including logo or lot trace code information. This information may be a 2D barcode or other human-readable markings. Note that 'x' is a placeholder for a 5-digit numerical code.

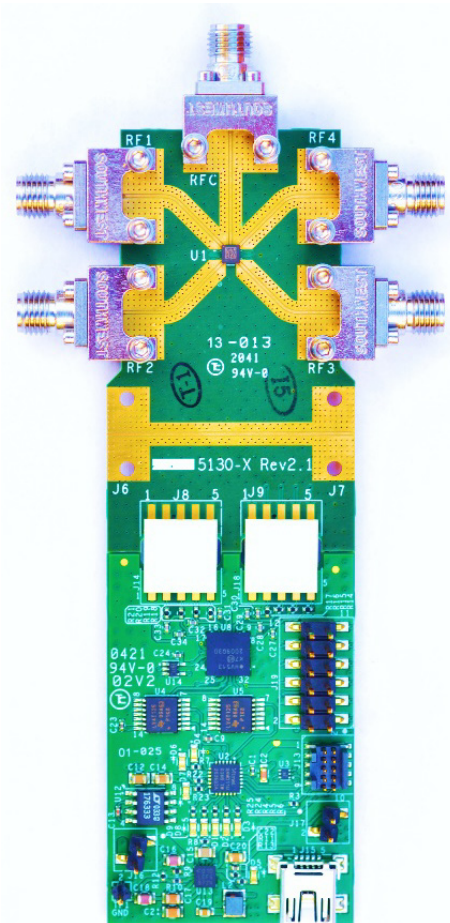
Legacy Product	New Product Name	
	Bulk	Tape and Reel <sup>1</sup>
<b>MM5130-03C</b>	<b>MM5130-03NDB</b>	<b>MM5130-03NDB-TR</b>
<b>MM5130-03</b>	<b>MM5130-03NDC</b>	<b>MM5130-03NDC-TR</b>

**Notes:**

1. 250pcs standard tape and reel increment

Various evaluation boards are available for the MM5130 device. Please see ordering information below and [Figure 9](#).

Part Number	EVK Description
<b>MM5130EVK1</b>	Standard evaluation board for MM5130 (w/SMA connector-QTY-7, 12GHz)
<b>MM5130EVK2</b>	High-performance evaluation board for MM5130 (w/Southwest connector-QTY-5, 18GHz improved performance)
<b>MM5130EVK2a</b>	High-performance evaluation board for MM5130 (w/Southwest connector-QTY-7, 18GHz improved performance)
<b>MM5130EVK3</b>	High-performance evaluation board for MM5130 Superport mode (w/Southwest connector-QTY-4, 26GHz improved performance)
<b>MM5130EVK3a</b>	High-performance evaluation board for MM5130 Superport mode (w/Southwest connector-QTY-6, 26GHz improved performance)



**Figure 9. MM5130EVK2 18 GHz Evaluation Board**

## Important Information

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### Contact Information

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For product technical questions and application information: [support@menlomicro.com](mailto:support@menlomicro.com).